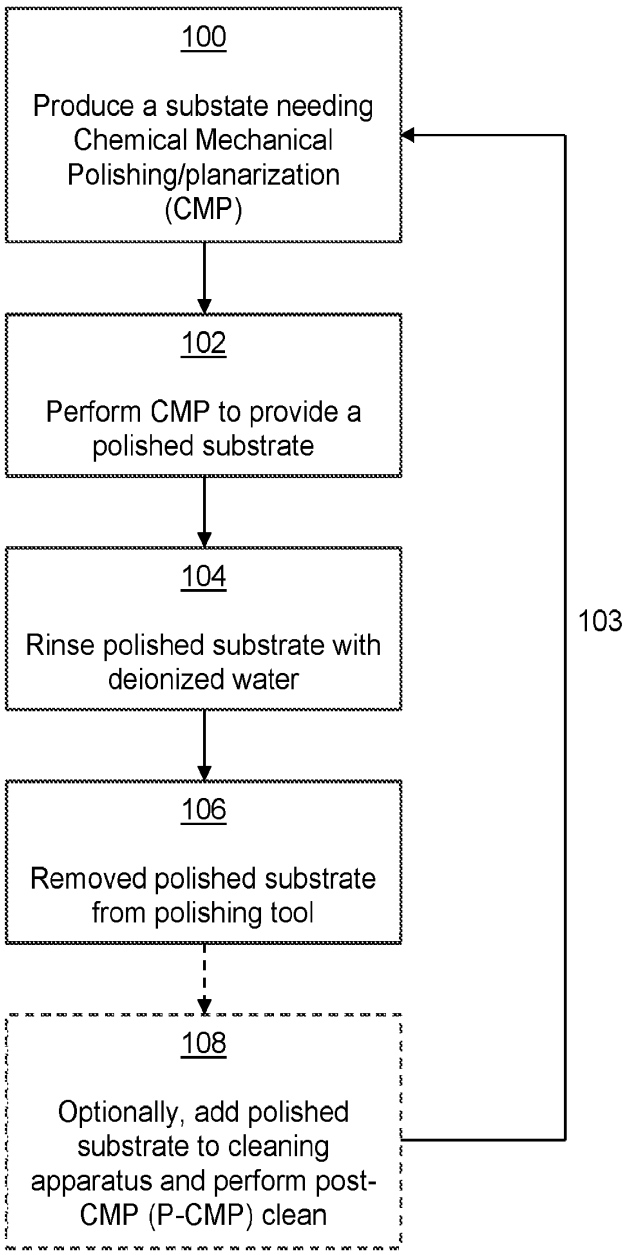

100
Produce a substate needing Chemical Mechanical Polishing/planarization (CMP)
102
Perform CMP to provide a polished substrate
104
Rinse polished substrate with deionized water
106
Removed polished substrate from polishing tool
108
Optionally, add polished substrate to cleaning apparatus and perform post-CMP (P-CMP) clean
103

FIG. 1

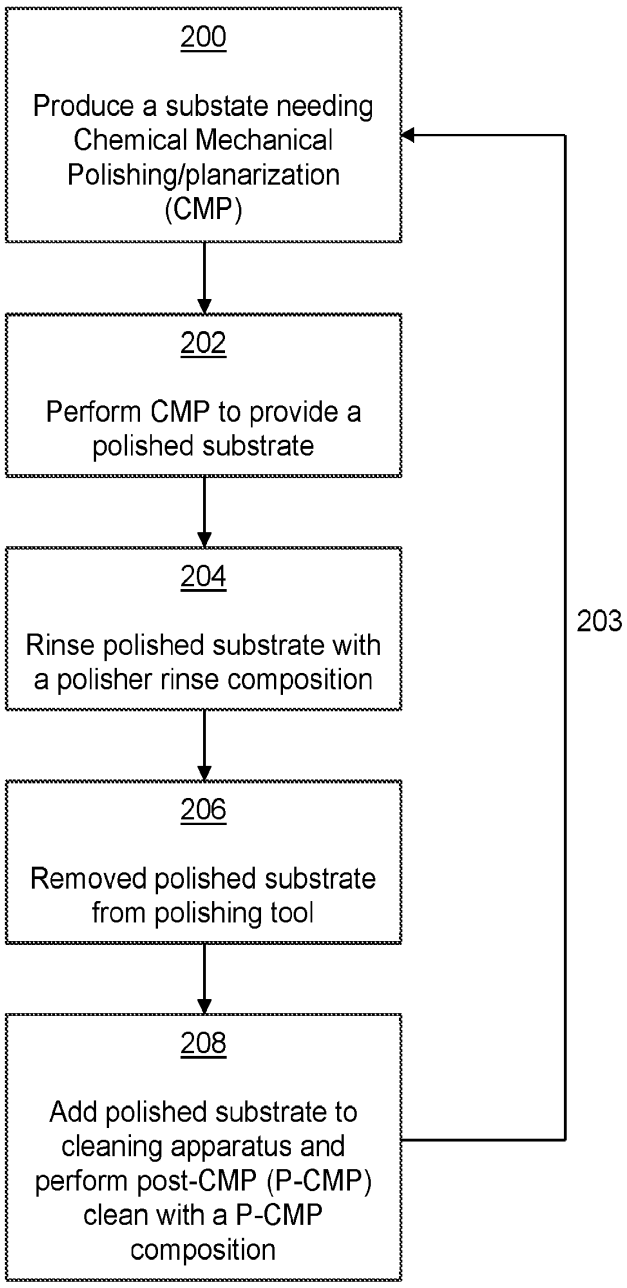
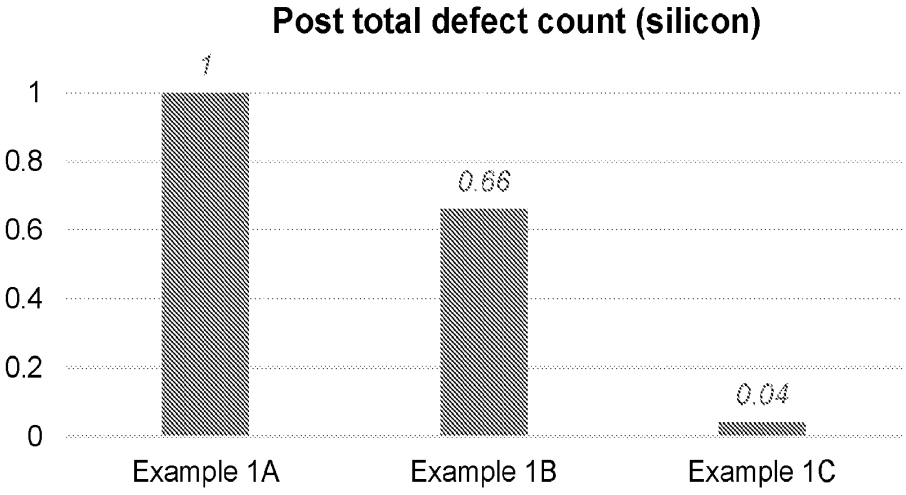
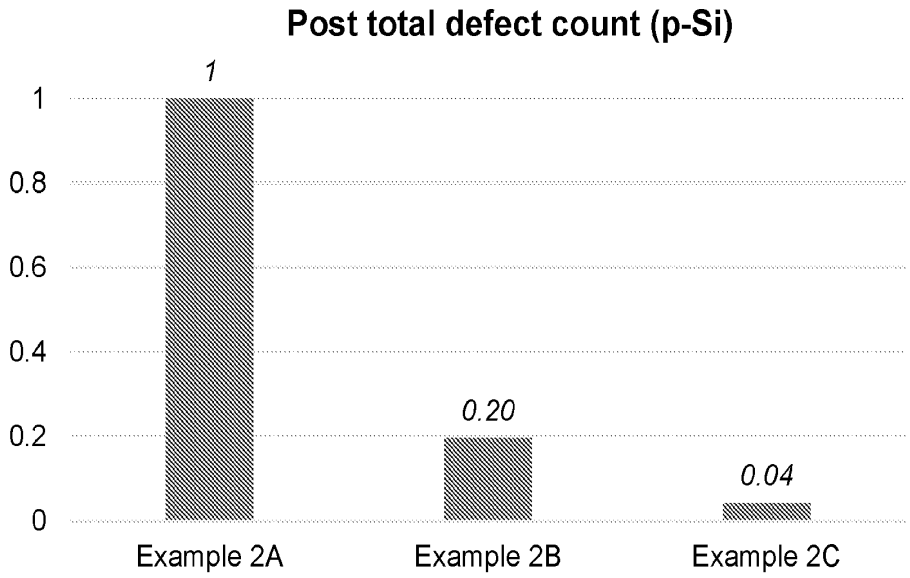

200
Produce a substate needing Chemical Mechanical Polishing/planarization (CMP)
202
Perform CMP to provide a polished substrate
204
Rinse polished substrate with a polisher rinse composition
206
Removed polished substrate from polishing tool
208
Add polished substrate to cleaning apparatus and perform post-CMP (P-CMP) clean with a P-CMP composition
203

FIG. 2



	Example 1A	*Example 1B*	*Example 1C*
CMP Slurry Comp.	CMP Slurry Comp. 1	CMP Slurry Comp. 1	CMP Slurry Comp. 1
Polisher Rinse Comp.	None	Deionized Water	Polisher Rinse Comp. 1 (10x)
P-CMP Comp.	Polisher Rinse Comp. 1 (200x)	Polisher Rinse Comp. 1 (200x)	Polisher Rinse Comp. 1 (200x)

FIG. 3

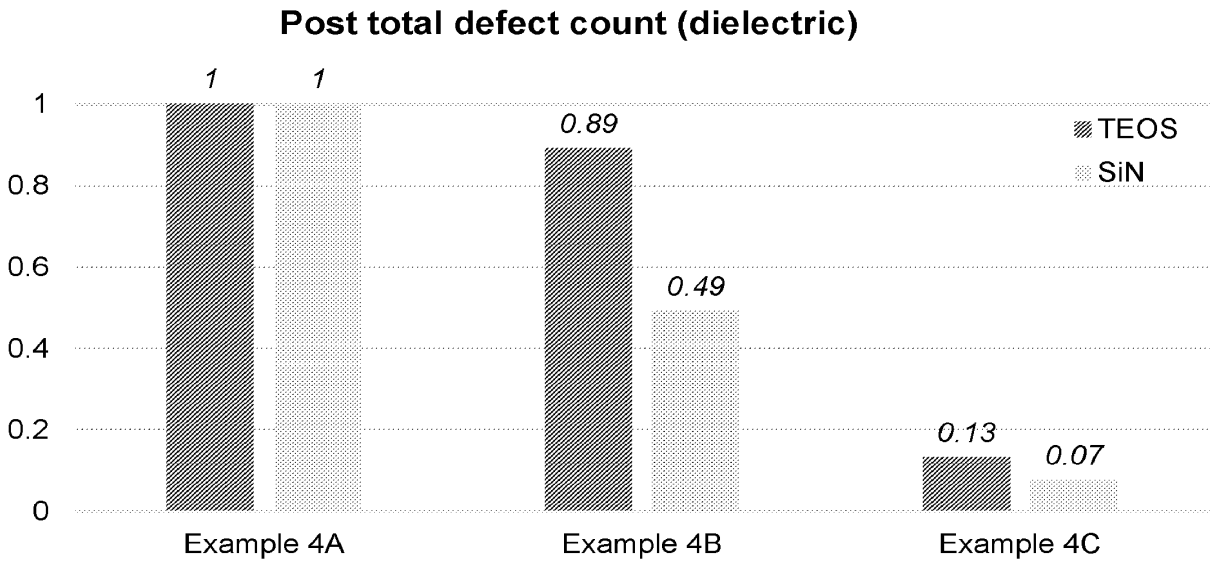


	Example 2A	*Example 2B*	*Example 2C*
CMP Slurry Comp.	CMP Slurry Comp. 2 (acidic)	CMP Slurry Comp. 2 (acidic)	CMP Slurry Comp. 2 (acidic)
Polisher Rinse Comp.	None	None	Polisher Rinse Comp. 1 (10x)
P-CMP Comp.	Comparative Polisher Rinse Comp. 1 (200x) (alkaline)	Polisher Rinse Comp. 1 (200x)	Polisher Rinse Comp. 1 (200x)

FIG. 4

CMP Slurry Comp.	*Example 3A*	*Example 3B*	*Example 3C*
Polisher Rinse Comp.	CMP Slurry Comp. 2	CMP Slurry Comp. 2	CMP Slurry Comp. 2
	None	Deionized Water	Polisher Rinse Comp. 1 (10x)
P-CMP Comp.	Polisher Rinse Comp. 1 (200x)	Polisher Rinse Comp. 1 (200x)	Polisher Rinse Comp. 1 (200x)

FIG. 5



	Example 4A	*Example 4B*	*Example 4C*
CMP Slurry Comp.	CMP Slurry Comp. 3	CMP Slurry Comp. 3	CMP Slurry Comp. 3
Polisher Rinse Comp.	None	Polisher Rinse Comp. 2 (200x)	Polisher Rinse Comp. 2 (10x)
P-CMP Comp.	Polisher Rinse Comp. 2 (200x)	Polisher Rinse Comp. 2 (200x)	Polisher Rinse Comp. 2 (200x)

FIG. 6